



Micro/Nano Manipulation Technologies for Flexible Electronics

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Deadline for manuscript
submissions:

closed (15 March 2022)

Message from the Guest Editors

Dear Colleagues,

Flexible electronics have developed rapidly and been widely used in the fields of medical treatment, biological engineering, and microelectronics industry. Now, a series of micro/nano manufacturing methods, such as lithography, soft lithography, nanoimprints, micro/nano 3D printing, etc., are widely used in the fabrication of flexible electronics. However, as the requirements of flexible electronic performance become higher, it is difficult to realize the manufacturing of higher-performance flexible electronics, such as heterogeneous, 3D or multilayer devices, only relying on one or several of the above manufacturing methods. Micro/nano manipulation technologies can solve the above problem by transferring, assembling, and integrating micro/nano components with different materials, sizes, and shapes to form heterogeneous, 3D, or multilayer devices. This opens up a new window for further improvement of the performance of soft electronics. Meanwhile, there are still some challenges in terms of the system, mechanism, and method of micro/nano manipulation for widespread industrial application.





Editor-in-Chief

Message from the Editor-in-Chief

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